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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



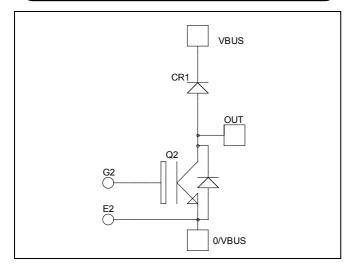






Boost chopper Trench + Field Stop IGBT3 Power Module





Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

Features

- Trench + Field Stop IGBT3 Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- **RoHS** Compliant

Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage		600	V
$I_{\rm C}$	Continuous Collector Current	$T_C = 25^{\circ}C$	430	
	Continuous Conector Current	$T_C = 80^{\circ}C$	300	A
I_{CM}	Pulsed Collector Current	$T_C = 25^{\circ}C$	500	
V_{GE}	Gate – Emitter Voltage		±20	V
P_{D}	Maximum Power Dissipation	$T_C = 25$ °C	1150	W
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^{\circ}C$	600A @ 550V	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
I _{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V, V_{CE} = 600V$				350	μΑ
V _{CE(sat)}	Collector Emitter Saturation Voltage	$V_{GE} = 15V$	$T_j = 25$ °C		1.4	1.8	V
V CE(sat)	Conector Emitter Saturation Voltage	$I_{\rm C} = 300 {\rm A}$	$T_j = 150$ °C		1.5		v
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 1.5 \text{ mA}$		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V, V_{CE} = 0V$				500	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit	
Cies	Input Capacitance	$\begin{aligned} V_{GE} &= 0V \\ V_{CE} &= 25V \\ f &= 1MHz \end{aligned}$			24		nF	
C_{oes}	Output Capacitance				1.5			
C_{res}	Reverse Transfer Capacitance				0.75			
$T_{d(on)}$	Turn-on Delay Time	Inductive Switch	ning (25°C)		115		ns	
T_{r}	Rise Time	$V_{GE} = \pm 15V$			45			
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 300V$ $I_{C} = 300A$			200			
$T_{\rm f}$	Fall Time	$R_G = 1.8\Omega$			55			
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) $V_{GE} = \pm 15V$ $V_{Bus} = 300V$ $I_{C} = 300A$ $R_{G} = 1.8\Omega$			120		ns	
$T_{\rm r}$	Rise Time				50			
$T_{d(off)}$	Turn-off Delay Time				250			
T_{f}	Fall Time				70			
Г	T	$V_{GE} = \pm 15V$ $V_{Bus} = 300V$ $I_{C} = 300A$	$T_j = 25^{\circ}C$		1.5		T	
Eon	Turn on Energy			$T_j = 150$ °C		2.7		mJ
E	T 25 F		$T_j = 25^{\circ}C$		8.55		mJ	
E _{off} Turn off Energy	Turn off Energy	$R_G = 1.8\Omega$	$T_{j} = 150^{\circ}C$		10.5		1113	

Chopper diode ratings and characteristics

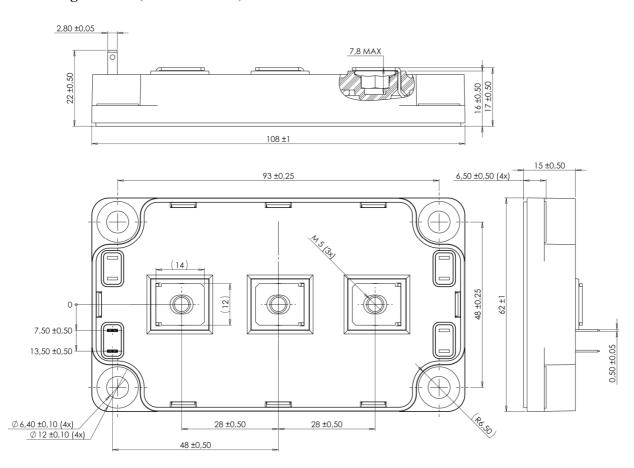
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	$V_R=600V$	$T_i = 25^{\circ}C$			150	μΑ
I_{F}	DC Forward Current		$T_{j} = 150^{\circ}C$ $Tc = 80^{\circ}C$		300	400	A
W	Diode Forward Voltage	$I_F = 300A$ $V_{GE} = 0V$	$T_i = 25^{\circ}C$		1.5	1.9	V
V_{F}			$T_{i} = 150^{\circ}C$		1.4		V
t _{rr}	Reverse Recovery Time	$I_F = 300A$ $V_R = 300V$ $di/dt = 3100A/\mu s$	$T_j = 25$ °C		130		ns μC
			$T_j = 150$ °C		225		
Q _{rr}	Reverse Recovery Charge		$T_j = 25^{\circ}C$		13.5		
			$T_{j} = 150^{\circ}C$		28.5		μС
E _r	Reverse Recovery Energy		$T_j = 25$ °C		3.5		mJ
			$T_{\rm j} = 150^{\circ}{\rm C}$		7.1		1113



Thermal and package characteristics

Symbol	Characteristic			Min	Тур	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance		IGBT			0.13	°C/W
			Diode			0.21	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range			-40		175	
T_{STG}	Storage Temperature Range			-40		125	°C
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	11.111
Wt	Package Weight	•				300	g

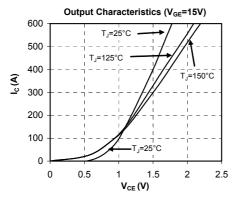
SP6 Package outline (dimensions in mm)

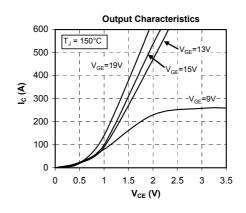


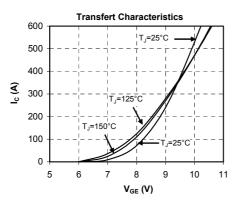
 $See \ application \ note \ APT0601 - Mounting \ Instructions \ for \ SP6 \ Power \ Modules \ on \ www.microsemi.com$

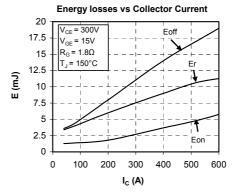


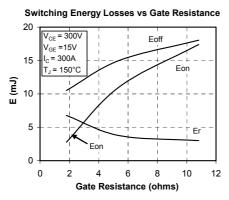
Typical Performance Curve

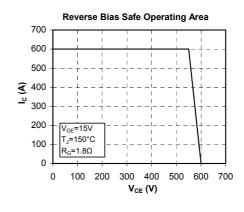


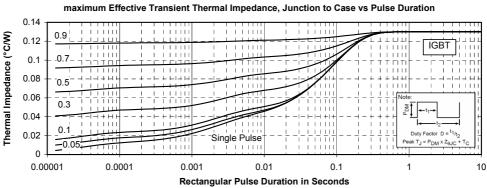




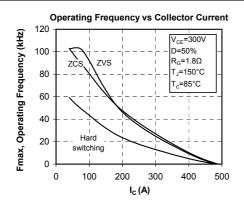


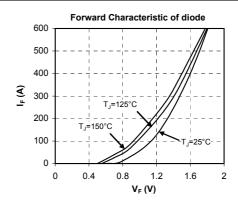


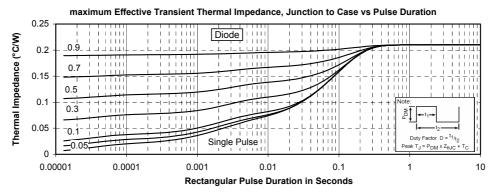














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